

= "bottom" >

Antimony (Sb<sub>2</sub>O<sub>3</sub>) Copper (Cu) Indium (In) Lead (Pb) Silver (Ag) Tin (Sn) **Substrate**  
**Components** Substrate Weight Substrate Material Substrate Core  
Material Bromine-Free

Copper Gold Nickel Substrate Core Material Solder Mask Triazol Other **UBM Components**  
Component Weight

Chromium (Cr) Copper (Cu) Nickel (Ni) Nickel-V (NiV) Titanium (Ti) Titanium-W  
(TiW) Tungsten (W) Vanadium (V) Top Passive Component 1 Material  
Type / PN Codes Component Weight

Weight Passive Component 1 **Passive Component 2** Material Type / PN Codes Component

Weight Passive Component 2 **Passive Component 3** Material Type / PN Codes Component

Weight Passive Component 3 **Passive Component 4** Material Type / PN Codes Component

Weight Passive Component 4 **Capacitor Components** Component

Weight Ceramic (BaTiO<sub>3</sub>) Copper (Electrode) **Crystal Components** Component

Silver (Ag) Aluminum (Al) Gold (Au) Chromium (Cr) Lead (Pb) Manganese (Mn) Nickel  
(Ni) Cobalt (Co) Copper (Cu) Iron (Fe) Silicon (Si) Tin (Sn) Zinc (Zn) Silica (SiO<sub>2</sub>) **Diode Components**  
Component Weight

Encapsulant (Phenolic Resin) Gold Wire Leadframe (Copper 194) Pellet (Chip) Terminal  
(SnAgCu) **Optocoupler Components** Component Weight

Die (Chip) Encapsulant (Phenolic Resin) Epoxy (Ag) Gold Wire Leadframe (Alloy 42) Potting  
Resin (Silicone) Terminal Plating (Sn) **Resistor Components** Component  
Weight

Component Weight **Transformer Components** Component

Weight

CopperFeO<sub>2</sub>MnO<sub>3</sub>ZnO

Notes:

1. Lead Form: GW - Gull Wing, TH - Through Hole.
2. Refer to product data sheet to confirm actual wire diameter.
3. 'ND' means None Detected, negligible amount present.

This part is qualified as lead-free.

Parts qualified as lead-free can be manufactured and supplied as lead-free, if and only if, the customer makes such requests to the Maxim Business Units for approval. The navigation bar on the EMMI website contains information regarding the lead-free process (e.g. MSL's, Peak reflow Temperatures, JEDEC methods, frequently asked questions and answers, lead-free package tables, and status/qualification plans for particular package types qualified as lead-free or in the qualification process).

This report was generated on 2020-07-09. For additional information, please visit the Maxim/Dallas Environmental Management and Materials Information website located at:

**<http://www.maximintegrated.com/emmi>**